

*Absolute Maximum Ratings (T_a=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current[1]	I _F	25	mA
	Reverse voltage	V _R	5	V
	Power dissipation	P _D	35	mW
	Peak Forward Current (Pulse Width ≤100uS, Duty Cycle=1%)	I _{FP}	1	A
Output	Collector-emitter voltage	V _{CEO}	20	V
	Emitter-collector voltage	V _{ECO}	5	V
	Collector current	I _C	20	mA
	Collector power dissipation	P _C	75	mW
Operating temperature		T _{opr}	-40~+85	°C
Storage temperature		T _{stg}	-40~+90	°C
Soldering temperature[2]		T _{sol}	260	°C
Manual soldering[2]		T _{sol}	300	°C

Notes:

1.Refer to the temperature ratingchart if the ambient temperature exceeds 25°C.

2.Complete soldering within 10 seconds for reflow soldering and within 3 seconds for manual soldering.

*Electrical / Optical Characteristics at T_A=25°C

Parameter		Symbol	Value			Conditions
			Min.	Typ.	Max.	
Input	Forward voltage	V _F	-	1.1V	1.3V	I _F =5mA
	Reverse current	I _R	-	-	10μA	V _R =5V
	Peak Wavelength	λ _p	-	940nm	-	I _F =20mA
Output	Collector current	I _C	50μA	150μA	500μA	I _F =5mA, V _{CE} =5V
	Collector dark current	I _D	-	-	100nA	V _{CE} =10V, 0LX
	Collector-emitter saturation voltage	V _{CE(sat)}	-	0.1V	0.4V	I _C =50μA, I _F =20mA
	Peak spectral sensitivity wavelength	λ _p	-	920nm	-	-
Rise time		t _r	-	8μsec	-	V _{CC} =5V, R _L =1KΩ I _C =100μA
Fall time		t _f	-	10μsec	-	

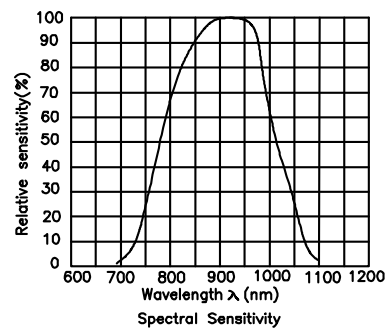


Fig.1 Forward Current vs. Forward Voltage

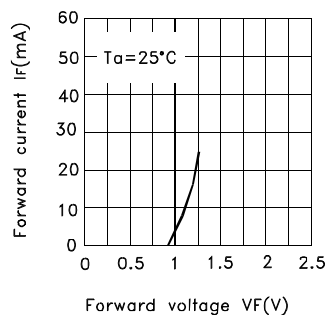


Fig.2 Collector Current vs. Forward Current

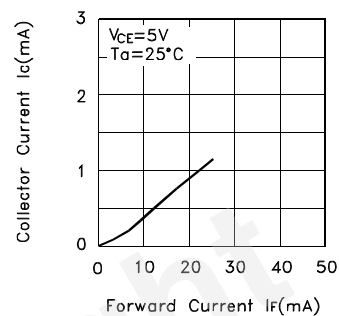


Fig.3 Collector Current vs. Ambient Temperature

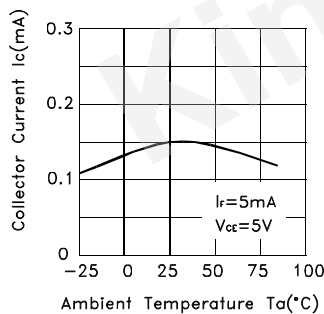


Fig.4 Collector-Emitter Saturation Voltage vs. Ambient Temperature

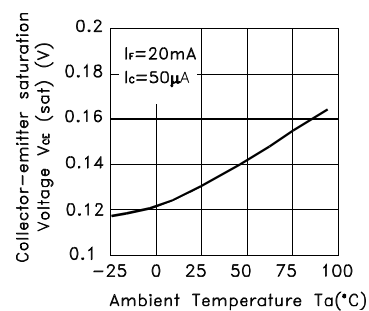


Fig.5 Forward Current vs. Collector Dissipation Temperature Rating

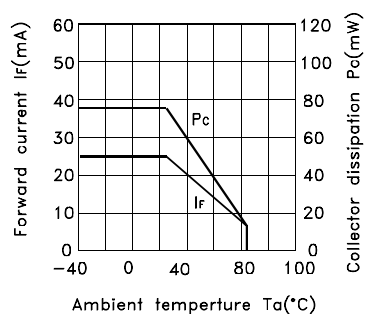


Fig.6 Forward Current vs. Collector-Emitter Voltage

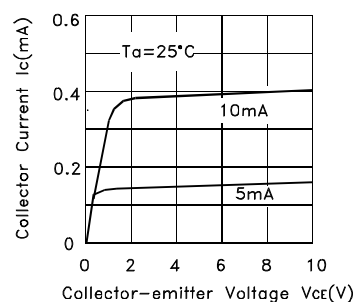


Fig.7 Relative Collector Current vs. Shield Distance(1)

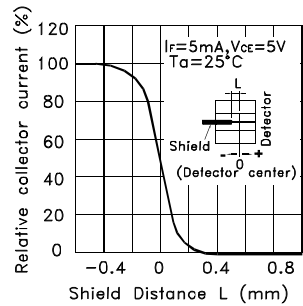


Fig.8 Relative Collector Current vs. Shield Distance(2)

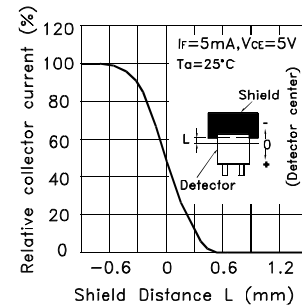
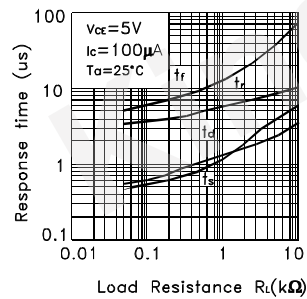
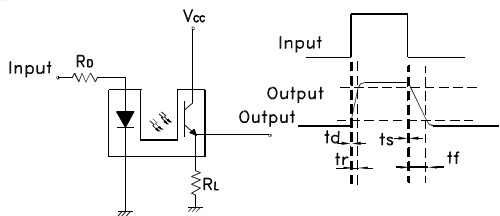


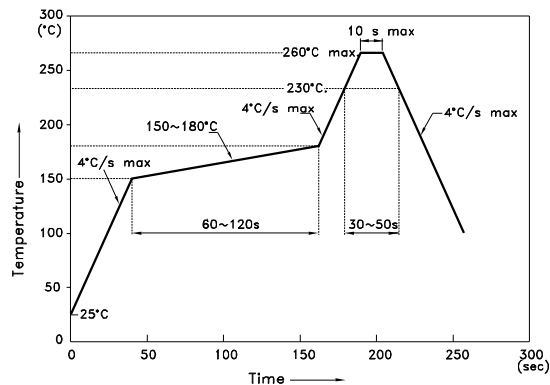
Fig.9 Response Time vs. Load Resistance



Test Circuit for Response Time



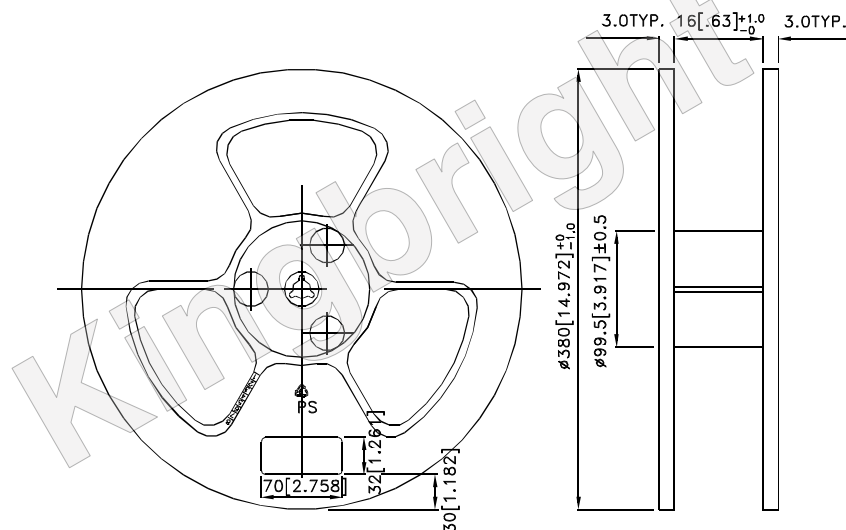
Reflow Soldering Profile For Lead-free SMT Process.



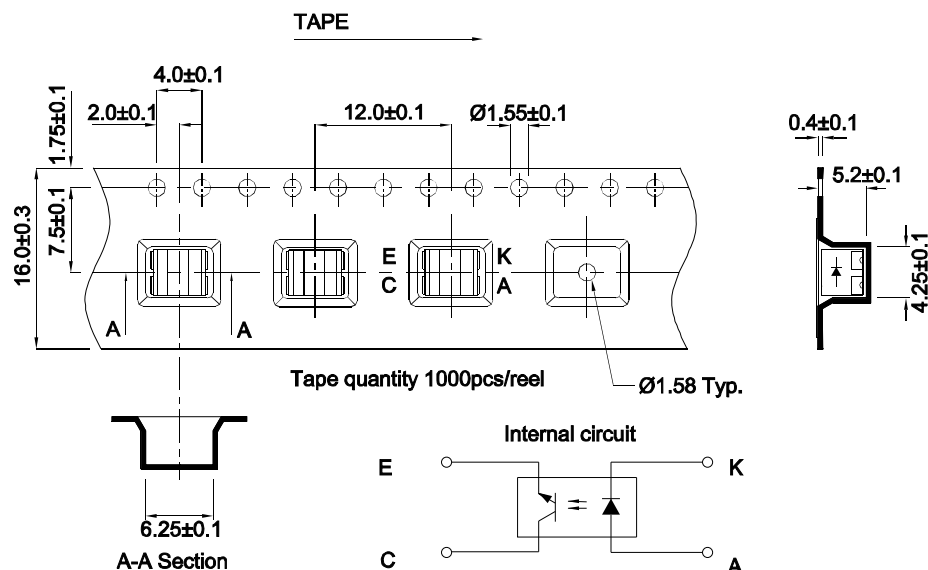
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Reel Dimensions (Units: mm)

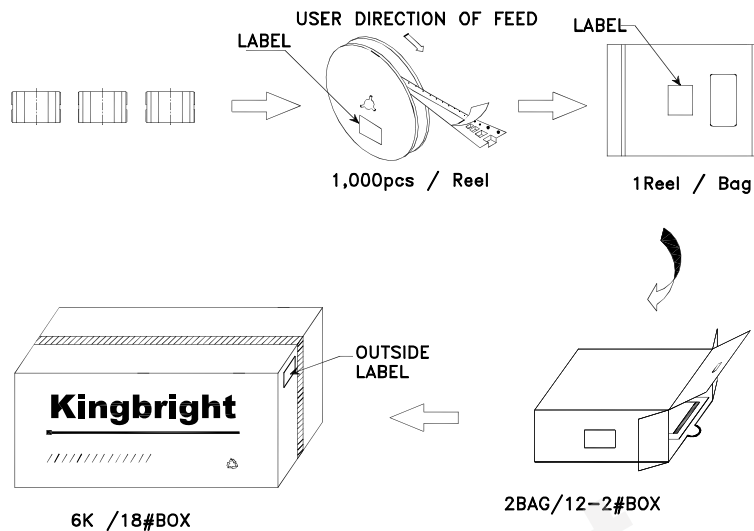


Tape Specifications (Units: mm)



PACKING & LABEL SPECIFICATIONS

KRB031



Kingbright	
P/NO: KRB031	
QTY: 1000 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
XXXXXXXXXX	
RoHS Compliant	

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